

5745459-2 ✓ ACTIVE

AMPLIMITE

TE Internal #: 5745459-2

PCB D-Sub Connectors, Receptacle, Board-to-Board, 37 Position, 2.77mm [.109in] Centerline, 2 Row, Row-to-Row Spacing 2.84 mm [.112 in]

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Connectors > D-Shaped Connectors > D-Sub Connectors > PCB D-Sub Connectors >

D-Sub Receptacle Assy: Vertical, Action Pin, Shell Size 4, 2.77mm



Connector & Housing Type: **Receptacle**

Connector System: **Board-to-Board**

Number of Positions: **37**

Centerline (Pitch): **2.77 mm [.109 in]**

Number of Rows: **2**

[All D-Sub Receptacle Assy: Vertical, Action Pin, Shell Size 4, 2.77mm \(9\)](#)

### Features

#### Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Grounding Indents                 | Without               |
| Grounding Straps                  | Without               |
| Grounded                          | No                    |
| Shell Type                        | All Plastic           |
| Connector & Housing Type          | Receptacle            |
| Connector System                  | Board-to-Board        |
| D-Sub Shell Size                  | 4                     |
| Sealable                          | No                    |
| Connector & Contact Terminates To | Printed Circuit Board |
| Shielded                          | No                    |
| Product Type                      | Connector             |

#### Configuration Features

|                       |          |
|-----------------------|----------|
| Number of Positions   | 37       |
| Number of Rows        | 2        |
| PCB Mount Orientation | Vertical |
| Preloaded             | Yes      |



### Body Features

|                                   |        |
|-----------------------------------|--------|
| Plastic                           | Yes    |
| Female Screwlock Material         | Brass  |
| Female Screwlock Plating Material | Nickel |
| Connector Profile                 | Low    |

### Contact Features

|   |                          |
|---|--------------------------|
| Contact Mating Area Plating Material          | Gold, Gold Flash         |
| Contact Underplating Material                 | Nickel, Palladium Nickel |
| PCB Contact Termination Area Plating Material | Tin                      |
| Contact Base Material                         | Copper Alloy             |
|   | 30 µin                   |

### Termination Features

|   |                          |
|---|--------------------------|
| Grounding Clips                             | Without                  |
| Termination Method to Printed Circuit Board | Through Hole - Press-Fit |
| Termination Post Length                     | 5.8 mm[.228 in]          |

### Mechanical Attachment

|                          |                                      |
|--------------------------|--------------------------------------|
| Panel Mount Feature      | Without                              |
| PCB Mount Retention      | With                                 |
| PCB Mount Retention Type | Action/Compliant Tail, Mounting Hole |
| Mating Retention         | With                                 |
| Mating Retention Type    | Female Screwlocks, Fixed             |
| Connector Mounting Type  | Board Mount                          |
| Mounting Hole Diameter   | 3.05 mm[.12 in]                      |

### Housing Features

|                    |                  |
|--------------------|------------------|
| Centerline (Pitch) | 2.77 mm[.109 in] |
| Housing Material   | Thermoplastic    |
| Housing Color      | Black            |

### Dimensions

|                             |                  |
|-----------------------------|------------------|
| Row-to-Row Spacing          | 2.84 mm[.112 in] |
| PCB Thickness (Recommended) | 2.36 mm[.093 in] |

### Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
|-----------------------------|----------------------------|



### Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

### Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

### Packaging Features

|                    |      |
|--------------------|------|
| Packaging Method   | Tray |
| Packaging Quantity | 52   |

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

|   |  |
|---|--|
| EU RoHS Directive 2011/65/EU                  | Compliant with Exemptions  |
| EU ELV Directive 2000/53/EC                   | Compliant with Exemptions  |
| China RoHS 2 Directive MIIT Order No 32, 2016 | Restricted Materials Above Threshold   |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2021 (211)<br>Candidate List Declared Against: JAN 2021 (211)<br>SVHC > Threshold:<br>Pb (2.5% in Component Part)<br><b>Article Safe Usage Statements:</b><br>Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free  |
| Solder Process Capability                     | Not applicable for solder process capability   |

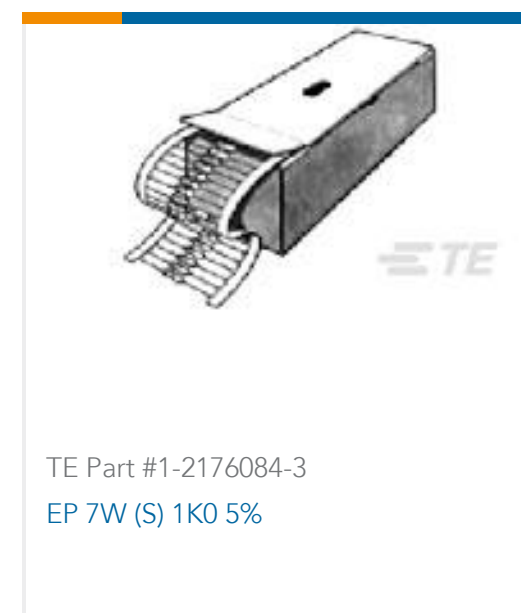
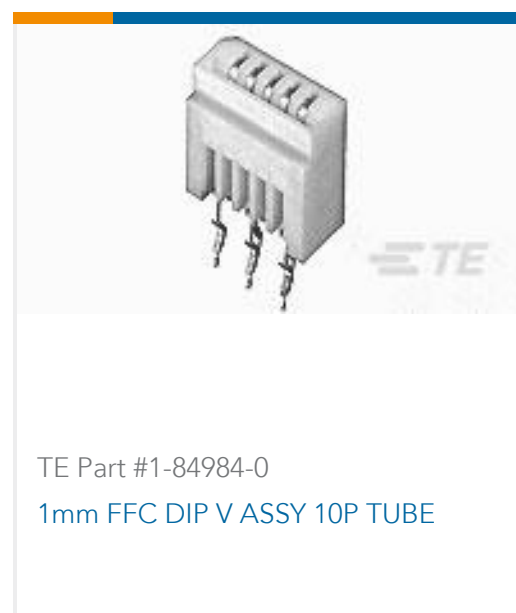
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



## Customers Also Bought



## Documents

### Product Drawings

[37 RCPT ACT PIN/AP LOW SCRLK](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_5745459-2\\_C.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_5745459-2\\_C.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_5745459-2\\_C.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.



### Datasheets & Catalog Pages

[AMPLIMITE Subminiature D Connectors - Straight Posted Connectors](#)

English

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### Product Specifications

[Application Specification](#)

English

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### Agency Approvals

[UL Report](#)

English